

Quantum-confined Stark effect at 1.3 μm in Ge/SiGe quantum-well structures

Mohamed-Saïd Rouifed, Papichaya Chaisakul,
Delphine Marris-Morini, Xavier Le Roux,
Samson Edmond, Jean-René Coudevylle,
and Laurent Vivien

Institut d'Electronique Fondamentale, Univ. Paris-Sud
CNRS UMR 8622, Orsay, FRANCE
E-mail: mohamed-said.rouifed@u-psud.fr

Jacopo Frigerio, Giovanni Isella, Daniel Chrastina
Laboratory for Epitaxial Nanostructures on Silicon and
Spintronics, Dipartimento di Fisica
Politecnico di Milano
Como, ITALY

Abstract—We demonstrate a room-temperature strong quantum confinement Stark effect (QCSE) in Ge/SiGe multiple quantum wells (MQW) heterostructures, embedded in PIN diode. The device is designed to operate at 1.3 μm , and QCSE is shown by photocurrent measurement in a surface illuminated device.

Keywords : *electroabsorption; Quantum Confined Stark Effect, Ge/SiGe MQW; optical interconnects.*

I. INTRODUCTION

Optical interconnects in chip-scale distance have been considered as an efficient alternative to electrical interconnects [1]. To integrate both electrical and optical devices on the same chips, the fabrication of the latter with processes compatible with Silicon CMOS (Complementary Metal-Oxide Semiconductor) is highly desirable [1]. Ge-based photonics has shown recently impressive results with demonstrations of light source [2], modulator [3], waveguides [4] and photodetectors [5-6]. Electroabsorption modulator based on Quantum Confined Stark Effect (QCSE) was formerly demonstrated with group III-V material [7], and recently in group IV material like Ge/SiGe multiple quantum well structures (MQW) [8-9]. Among the advantages of MQW structures in comparison to bulk materials, MQW structures can be engineered to shift the operating wavelength of QCSE. In this work we demonstrate room-temperature QCSE in Ge/SiGe MQWs working at 1.3 μm .

II. DEVICE DESIGN AND FABRICATION

To work at 1.3 μm , a blue shift of the absorption edge from 0.8eV for bulk Ge to 0.95eV is needed. Different methods can be used to achieve this wavelength shift, among them are the increase of the confinement in the quantum wells by, for example, using very narrow quantum well, or the use of SiGe material as the quantum well or the use of strain engineering to increase the band gap energy in Ge quantum well [10].

We designed Ge/SiGe QW structure by strain engineering in order to work at 1.3 μm . In comparison with our first demonstration [9] working at 1.4 μm Ge concentration is now decreased in the barriers and in the relaxed buffer (a strain compensated structure is used). Therefore, Ge well is more compressively strained relative to the relaxed buffer and its

band gap energy is increased. In the fabricated device, 21% of Si is used in the relaxed buffer and 35 % in SiGe barriers while the wells are made of pure Ge.

The Ge/Si_{0.35}Ge_{0.65} MQW structure is embedded in a PIN diode, allowing large electrical field to be applied across the active region. The structure is grown by low energy plasma-enhanced chemical vapor deposition (LEPECVD) [11]. On a 100mm Si(001) substrate, a 1 μm Si_{1-y}Ge_y graded buffer was linearly grown from y=0 to y=0.79 of germanium concentration with rate of 7%/ μm . This graded buffer allows achieving very high quality QW structures despite the large lattice mismatch between Si and Ge, which is very useful to study material properties. After this graded buffer, 2 μm of Si_{0.21}Ge_{0.79} is added forming a fully relaxed virtual substrate (VS) on where PIN diode can be grow. P region was then deposited, which consists a 500nm boron-doped Si_{0.21}Ge_{0.79} layer, followed by 50nm Si_{0.21}Ge_{0.79} spacer. The MQW region is formed by 10 nm of Ge (well) and 15nm Si_{0.35}Ge_{0.65} (barrier) which are repeated 20 times to achieve 20 QW's. This thick structure is possible thanks to the average Ge concentration in Ge/SiGe MQW layers equal that of the buffer layer. Finally, a 50nm Si_{0.21}Ge_{0.79} cap layer and 100nm phosphorus-doped Si_{0.21}Ge_{0.79} n-type layer are added to form the top contact.

A square surface 100 μm x114 μm illuminated PIN diode was fabricated for the photocurrent measurement. UV lithography and dry etching were used to pattern the mesa. For metallic contacts, 20nm of Ti and 300nm of Au are evaporated and lifted-off for both n and p contacts. The schematic view and optical microscope image of the fabricated device are show in figure (1).

III. EXPERIMENTAL RESULTS

Photocurrent measurements of the Ge/SiGe MQWs at several reverse bias voltages were performed at room temperature. The incident light, normal to the surface of diode, was randomly polarized from tunable laser from 1245nm to 1350nm with step of 1nm. A chopper was used to modulate the input light at 0.5 kHz and a lock-in amplifier permits to measure precisely the photocurrent spectra, provided that a reference photocurrent measurement at a given wavelength is used for normalization.

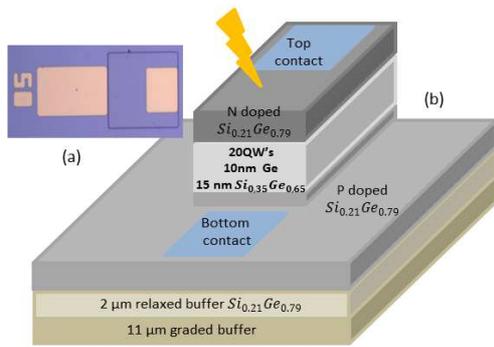


Figure 1. (a). Optical microscopic top view of device. (b). Cross section showing the different layers.

To estimate the strength of band-to-band absorption for light incident perpendicular to QW structures, the fraction of light absorbed per well γ_{well} , can be calculated by the following equation in case of $\gamma_{well} \ll 1$ [12]:

$$N \times \gamma_{well} = \frac{\Delta P}{P_0} \quad (1)$$

Where ΔP the optical power absorbed in the MQW's and P_0 is the incident power. N is the number of wells in the intrinsic region. To calculate the fraction of light absorbed per well from the photocurrent measurements, the following relation is used [9]:

$$I_{ph} = \frac{eP_0N\gamma_{well}(\lambda)\lambda}{hc} \quad (2)$$

Where P_0 is the incident optical power, taking into account the reflection at the surface of device, h is Planck constant, e is electron charge, c is the speed of light and λ is wavelength.

The absorption spectra obtained from this method is reported in figure (2). As a consequence of the confinement effect in the MQW and the strain between Ge in QW and the VS, a shift of absorption edge from 0.8eV for bulk Ge to 0.96eV is clearly observed. At low reverse bias (-1V is used in order to have electric field applied across the entire PIN diode, in order to collect all photogenerated carriers), clear exciton peak is seen in the spectra at 1.277 μm which can be attributed to the transition between heavy hole level and electronic state at Γ point. It can be noted that at higher wavelength (1.34 μm), the residual fraction of light absorbed, attributed to the indirect absorption in the quantum wells is rather small in comparison with direct gap absorption.

When the reverse bias is increased, the two main characteristics of QCSE are observed in the measured spectra: the absorption edge is shifted toward larger wavelength, and the excitonic peak absorption is decreased. From those two effects, absorption per well at 1.3 μm goes from 1.5×10^{-3} to 3.5×10^{-3} when bias varies from 1 to 5V.

IV. CONCLUSION

In this work, we demonstrate the possibility to engineer Ge/SiGe MQW structures. Strong quantum confined Stark effect was demonstrated at 1.3 μm , which will enable reliable

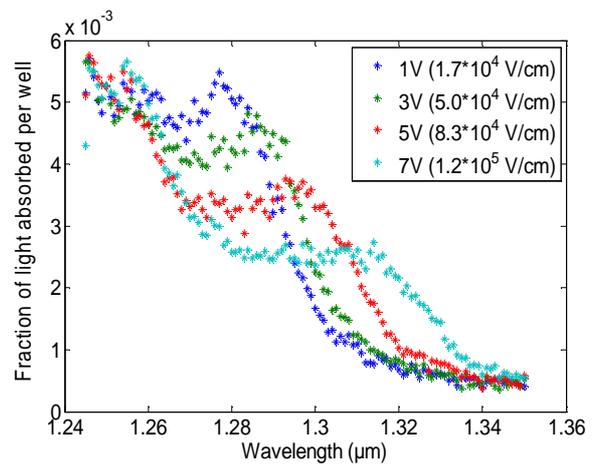


Figure 2. Absorption spectra for different applied electrical field from photocurrent measurement.

design of integrated photonic devices based on Ge/SiGe MQW structures.

ACKNOWLEDGMENT

The research has received funding from the French ANR under project GOSPEL (Direct Gap related Optical Properties of Ge/SiGe Multiple Quantum Wells). The fabrication of the device was performed at the nano-center CTU-IEF-Minerve, partially funded by the "Conseil Général de l'Essonne". Financial support for the epitaxial growth was provided by the Cariplo foundation through NANOGAP project

REFERENCES

- [1] D. A. B. Miller, "rationale and challenges for optical interconnects to electronic chips," IEEE Proceedings, 88 (6), 728-749 June 2000.
- [2] X. Sun, et al "Toward a Germanium Laser for Integrated Silicon Photonics", IEEE Journal of Selected Topics in Quantum Electronics, 16 (1), 124-131, January/February 2010.
- [3] P. Chaisakul, et al "23 GHz Ge/SiGe multiple quantum well electro-absorption modulator" Optics Express, 20 (3), 3219-3225, (2012).
- [4] O. Fidaner, et al "Optical Link on Silicon Employing Ge/SiGe Quantum Well Structures", LEOS Meeting, 852-853 (2007).
- [5] P. Chaisakul, et al "Ge/SiGe multiple quantum well photodiode with 30 GHz bandwidth", Applied Physics Letters, 98, 131112, 2011.
- [6] O. Fidaner, et al "Ge-SiGe Quantum-Well Waveguide Photodetectors on Silicon for the Near-Infrared", IEEE Photonics Technology Letters, 19 (20), 1631-1633, 2007.
- [7] D. A. B Miller, et al, "Band-edge electroabsorption in quantum well structures: The quantum-confined stark effect", Phys. Rev. Let., 53 (22), 1984
- [8] Y-H. Kuo, et al, "Strong quantum-confined Stark effect in germanium quantum-well structures on silicon", Nature, 437, 1334-1336 2005.
- [9] P. Chaisakul, et al "Quantum-confined Stark effect measurements in Ge/SiGe quantum-well structures", Opt. Let. , 35(17), 2913-2915, 2010.
- [10] L. Lever, et al "Design of Ge-SiGe Quantum-Confined Stark Effect Electroabsorption Heterostructures for CMOS Compatible Photonics", Journal of Lightwave Technology, 28 (22) 3273-3281, November 2010.
- [11] G. Isella, et al "Low-energy plasma-enhanced chemical vapor deposition for strained Si and Ge heterostructures and devices," Solid State Electron. 48, 1317-1323 (2004).
- [12] P. Blood, "On the dimensionality of optical absorption, gain, and recombination in Quantum-Confined structures", Journal of Quantum Electronics, 36 (3), (2000).